



New Industry 4.0 Advances in Industrial IoT and Visual Computing for Manufacturing Processes: Volume III

Guest Editors:

Prof. Dr. Luis Norberto López De Lacalle

The Aeronautics Advanced
Manufacturing Center-CFAA,
48170 Zamudio, Biscay, Spain

Dr. Jorge Posada

Vicomtech Technological Center,
Paseo Mikeletegi 57, E-20009
Donostia/San Sebastián, Spain

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Message from the Guest Editors

Dear Colleagues,

Over the last three years, industrial factories have been experiencing a rapid digital transformation because of the introduction of emerging ICT technologies, such as the Industrial Internet of Things (IIoT), industrial big data and cloud technologies, deep learning and deep analytics, artificial intelligence, intelligent robotics, cyber-physical systems, digital twins, and visual computing (including augmented reality, visual analytics, cognitive computer vision, new HMI interfaces, and simulation and computer graphics), among others. This is evident in the global trend of Industry 4.0 and related initiatives, which are present in one way or another in many different production strategies at an international level (Industrie 4.0, Germany; industrial Internet, USA; Industrie du Futur, France; made in China 2025, China; etc.).

This Special Issue is an opportunity for the scientific community to present recent research regarding industrial IoT and visual computing as key aspects of Industry 4.0 for manufacturing processes.

Prof. Dr. Luis Norberto López De Lacalle

Dr. Jorge Posada

Guest Editors





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Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo

Dipartimento di Fisica,
Politecnico di Milano, Piazza L.
da Vinci 32, 20133 Milano, Italy

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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